

| Item | Designator | Description | Manufacturer | PartNumber | Quantity |
|------|------------------------------------|---|-----------------------|-------------------------|----------|
| 1 | AA1 | Printed Circuit Board | TBD | Used in BOM Report | 1 |
| 2 | C1, C2, C3, C20, C21, C22 | CAP, CERM, 2.2uF, 100V, +/-10%, X7R, 1210 | Taiyo Yuden | HMK325B7225KN-T | 6 |
| 3 | C4, C18 | CAP, CERM, 1uF, 16V, +/-10%, X7R, 0603 | MuRata | GRM188R71C105KA12D | 2 |
| 4 | C5 | CAP, CERM, 0.1uF, 100V, +/-10%, X7R, 0805 | TDK | C2012X7R2A104K | 1 |
| 5 | C6, C14, C16, C24 | CAP, CERM, 0.1uF, 50V, +/-10%, X7R, 0603 | TDK | C1608X7R1H104K | 4 |
| 6 | C7, C19 | CAP, CERM, 0.1uF, 100V, +/-10%, X7R, 0603 | MuRata | GRM188R72A104KA35D | 2 |
| 7 | C8, C11, C17 | CAP, CERM, 100pF, 50V, +/-5%, COG/NP0, 0603 | AVX | 06035A101JAT2A | 3 |
| 8 | C9, C10, C27, C28 | CAP ALUM 22UF 12.5V 20% SMD | Panasonic-ECG | EEF-CD1B220R | 4 |
| 9 | C12, C29 | CAP, CERM, 2700pF, 100V, +/-5%, X7R, 0603 | AVX | 06031C272JAT2A | 2 |
| 10 | C13 | CAP, CERM, 0.047uF, 50V, +/-10%, X7R, 0603 | TDK | C1608X7R1H473K | 1 |
| 11 | C15, C23 | CAP, CERM, 2200pF, 50V, +/-10%, X7R, 0603 | Kemet | C0603C222K5RACTU | 2 |
| 12 | C25, C26 | CAP, CERM, 100pF, 50V, +/-5%, COG/NP0, 0603 | MuRata | GRM1885C1H101JA01D | 2 |
| 13 | D1, D2, D3, D4 | Diode, Schottky, 100V, 0.15A, SOD-123 | Diodes Inc. | BAT46W-7-F | 4 |
| 14 | D5, D6, D7, D8 | Diode, Schottky, 30V, 0.2A, SOD-323 | Diodes Inc. | BAT54WS-7-F | 4 |
| 15 | FID1, FID2, FID3, FID4, FID5, FID6 | Fiducial mark. There is nothing to buy or mount. | N/A | N/A | 6 |
| 16 | GND, GND V | Test Point, TH, Miniature, Black | Keystone | 5001 | 2 |
| 17 | J1, J2 | PC PIN .040 DIA 3102-2 SERIES | Mill -Max | 3102-2-00-21-00-00-08-0 | 2 |
| 18 | J3, J4 | CIRCUIT PIN PRNTD .188" .084" | Mill -Max | 3144-2-00-21-00-00-08-0 | 2 |
| 19 | L1, L2 | Inductor, Shielded E Core, Ferrite, 10.0uH, 34A, .0023 ohm, SMD | Coilcraft | VER2923-103KL | 2 |
| 20 | Q1, Q2, Q5, Q6 | MOSFET, N-CH, 80V, 55A, PG-TDSON-8 | Infineon Technologies | BSC123N08NS3 G | 4 |
| 21 | Q3, Q4, Q7, Q8 | MOSFET, N-CH, 80V, 100A, PG-TDSON-8 | Infineon Technologies | BSC047N08NS3 G | 4 |
| 22 | Q9, Q10, Q11, Q12 | TRANS BIPO PNP 30V 1A SOT-323 | Diodes Inc. | 2DB1694-7 | 4 |
| 23 | R1, R13 | RES, 0 ohm, 5%, 0.1W, 0603 | Vishay-Dale | CRCW06030000Z0EA | 2 |
| 24 | R2, R6 | RES, 10.0k ohm, 1%, 0.1W, 0603 | Vishay-Dale | CRCW060310K0FKEA | 2 |

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| 25 | R3 | RES, 1.00 ohm, 1%, 0.125W, 0805 | Vishay-Dale | CRCW08051R00FNEA | 1 |
| 26 | R4 | RES, 133k ohm, 1%, 0.1W, 0603 | Vishay-Dale | CRCW0603133KFKEA | 1 |
| 27 | R5 | RES, 2.49k ohm, 1%, 0.1W, 0603 | Vishay-Dale | CRCW06032K49FKEA | 1 |
| 28 | R7, R23 | RES, 73.2k ohm, 1%, 0.1W, 0603 | Vishay-Dale | CRCW060373K2FKEA | 2 |
| 29 | R8, R16 | RES, 1.00 ohm, 1%, 0.25W, 1206 | Vishay-Dale | CRCW12061R00FNEA | 2 |
| 30 | R9 | RES, 3.32k ohm, 1%, 0.1W, 0603 | Vishay-Dale | CRCW06033K32FKEA | 1 |
| 31 | R10, R19 | RES, 0.003 ohm, 1%, 0.5W, 2010 | Vishay-Dale | WSL20103L000FEA | 2 |
| 32 | R11 | RES, 49.9k ohm, 1%, 0.1W, 0603 | Vishay-Dale | CRCW060349K9FKEA | 1 |
| 33 | R18 | RES, 69.8k ohm, 1%, 0.1W, 0603 | Vishay-Dale | CRCW060369K8FKEA | 1 |
| 34 | R22 | RES, 4.99k ohm, 1%, 0.1W, 0603 | Vishay-Dale | CRCW06034K99FKEA | 1 |
| 35 | R24 | RES, 49.9 ohm, 1%, 0.1W, 0603 | Vishay-Dale | CRCW060349R9FKEA | 1 |
| 36 | R25, R26, R27, R28 | RES, 100 ohm, 1%, 0.1W, 0603 | Vishay-Dale | CRCW0603100RFKEA | 4 |
| 37 | U1 | IC CTRL SYNC BUCK DUAL 32-LLP | National Semiconductor | LM5119PSQE/NOPB | 1 |
| 38 | VIN, VOUT | Test Point, TH, Miniature, Red | Keystone | 5000 | 2 |
| 39 | EN2, Sync, TP IN, TP OUT | Test Point, TH, Miniature, Red | Keystone | 5000 | 0 |

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